SCOPE OF ACCREDITATION

Electronics - Printed Board Assemblies

Electronic Source Company
16032 Arminta St
Van Nuys, CA 91406

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7000 Rev A - AUDIT CRITERIA FOR NADCAP ACCREDITATION

AC7120 Rev E - Nadcap Audit Criteria for Printed Board Assemblies (to be used on audits on/after 9 April 2017) (CANNOT BE COMBINED WITH AC7119 or AC7121)

03–Company Information (mandatory)
04– General (mandatory)
05– Outsourced Processes (mandatory)
06– Process Control (mandatory)
07– Visual Acuity (mandatory)
08– Customer Data (mandatory)
09– Electrostatic Discharge (ESD) (mandatory)
10– Material Management (mandatory)
13.1– In–Process Verification / Inspection: General (mandatory)
13.2– In–Process Verification / Inspection: Visual (mandatory)
15– Cleanliness
16– Final Inspection (mandatory)
17– Rework (mandatory)
In–Process Verification / Inspection: AOI
In–Process Verification / Inspection: X–Ray
Kitting
Moisture Sensitive Components and Materials
Secondary Assembly: Bonding
Secondary Assembly: Compliant Pin (Press Fit) Connector Installation
Secondary Assembly: Jumper Wire Installation
Secondary Assembly: Mechanical Part Installation
Secondary Assembly: Stranded Wire Tinning
Secondary Assembly: Wire Cutting & Stripping

AC7120/2 - General Soldering of Printed Board Assemblies (to be used on audits on/after 9 April

2017)

03– General (mandatory)
05.1– Part Placement: General (mandatory)
Build Through / Build Short
Electronic Component Preparation for Preassembly Process
Gold Removal
Hand Soldering
Part Placement: Clinched Component Leads
Part Placement: Manual

AC7120/3 - Plated Through Hole Technology (requires AC7120/2) (to be used on audits on/after 9 April 2017)

Selective Soldering

AC7120/4 Rev A - Surface Mount Technology (requires AC7120/2) (to be used on audits on/after 3 March 2019)

05– Automated Part Placement (mandatory)
06– Reflow Soldering (mandatory)
Preparation
Solder Paste Printing: Stencil Printing

AC7120/5 - Mixed Metallurgy for BGAs (requires AC7120/2 and AC7120/4) (to be used on audits on/after 9 April 2017)

03– Lead–Free Control Plan (LFCP) (mandatory)
04– Qualification for Assemblies Containing BGAS (mandatory)

AC7120/6 - Lead Free Soldering (requires AC7120/2) (to be used on audits on/after 9 April 2017)

03– Lead–Free Control Plan (LFCP) (mandatory)
04– Process Control (mandatory)
05– Training (mandatory)

AC7120/7 Rev A - Conformal Coating of Printed Board Assemblies (to be used on audits on/AFTER 05-Nov-2023)

04– Material (mandatory)
05– Material and Equipment Compatibility (mandatory)
06– Preparation / Cleaning (mandatory)
07– Application / Drying / Curing (mandatory)
08– Thickness (mandatory)
09– Inspection (mandatory)
10– Rework (mandatory)
11– Training (mandatory)

AC7120/8 - Encapsulation (to be used on audits on/after 9 April 2017)

AC7120/9 - Programming (to be used on audits on/after 9 April 2017)
04– General (mandatory)
06– Circuit Card Assembly Programming

AC7120/10 - Final Testing (to be used on audits on/after 9 April 2017)
04– General

AC7120/12 - Nadcap Audit Criteria for Depaneling (to be used on audits on/after 30 June 2019)
03.1– Inspection (mandatory)
03.3 – Process Development and qualifications (mandatory)
Mechanical Router Process
Preservation and Packing of Depaneled Images (mandatory)
Programming